



Course: M.Tech. (Electronics & Communication Engineering)	Name of Faculty: Dr.Nalesh S
Topic: 18-437-0107 VLSI Technology & Design	Semester: FIRST
Lecture Hall: 118	Timings: as per CBCS

<i>Week and date</i>	<i>Lecture topics</i>	<i>Assignments</i>	<i>Remarks</i>
Week 1 (8 th July 19)	Module 1: Introduction to CMOS VLSI Introduction, Semiconductors, Band Diagrams, Fermi Level, Intrinsic Semiconductor, Doping, P and N type, Current Transport Mechanisms PN Junctions, Terminology, Quantitative Analysis, Static Behavior		
Week 2 (15 th July 19)	PN Junction Capacitance, MOS Capacitor, Operating regions, Quantitative Analysis	Class Test-1 Research Topic for Presentation	
Week 3 (22 nd July 19)	MOS Capacitor CV characteristics, MOS transistor Ideal I-V characteristics, MOSFET Non Ideal Effects, NMOS Inverters	Class Test-2	
Week 4 (29 th July 19)	MOSFET capacitances and resistances, Complementary MOS Logic - Inverter, Combinational Logic, NAND/NOR gates Module 2: Combinational Circuit Design Static CMOS Inverter, Static Behavior, Static CMOS Inverter, Dynamic Behavior, Transient Response	Class Test-3	
Week 5 (5 th Aug 19)	Static CMOS Inverter, resistance and capacitance model, Sizing of Inverters, Sizing chain of inverters for optimum delay, Power dissipation in static CMOS inverters	Class Test-4	
Week 6 (12 th Aug 19)	First Internals		
Week 7 (19 th Aug 19)	Complementary CMOS design -Pull up and Pull Down Networks, Static behavior, VTC Dynamic behavior, Delay dependence on Fanin and Fanout, Sizing of Complementary CMOS gates	Class Test-5	
Week 8 (26 th Aug 19)	Logical Effort, Sizing an chain of gates,	Presentation-1	
Week 9 (2 nd Sep 19)	Ratioed Logic, Pass-Transistor Logic, Transmission gates, Dynamic Logic, Static Latches and Registers, Dynamic Latches and Registers	Class Test-6	
Onam Vacation			

Week 10 (17 th Sep 19)	Pipelining, Time borrowing, Timing Metrics, Memory Cells		
Week 11 (23 rd Sep 19)	Module 4: CMOS Fabrication and Layout Fabrication Process -Silicon wafer preparation, FEOL processing, Diffusion of impurities, ion implantation, annealing, oxidation, lithography	Class Test-7	
Week 12 (30 th Sep 19)	Chemical Vapour Deposition, epitaxial growth, BEOL process- metallization, patterning, wire bonding, packaging. MOS Layers, Layout Design Rules, Gate Layout		
Week 13 (7 th Oct 19)	Module 5: CMOS Scaling and Sub-Micron Trends: Propagation Delays, Logic and Interconnect delays, Scaling Factors for Device Parameters, Constant field scaling and constant voltage scaling	Presentation-2	
Week 14 (14 th Oct 19)	Challenges going to sub-100 nm MOSFETs Multiple gate MOSFETs, FinFETs, Silicon-on-insulator	Class Test-8	
Week 15 (21 st Oct 19)	Module 3: VLSI Design Flow Custom, Semicustom and Structured-Array Design Approaches, Semicustom Design Flow Design Capture, Register Transfer Logic, Functional, Simulation, High Level Synthesis, Logic Synthesis, Timing Simulation, Static Timing Analysis, Power Analysis, Planning, Partitioning, Placement and Routing, Extraction, Packaging, IC testing		
Week 16 (28 th Oct 19)	Second Internals		
Week 17 (6 th Nov 19)	Publication of Sessional		